RNEY)

DECLAI (OR PATENT APPLICATION (WITH POWER (

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR TRANSFER MOLDING ENCAPSULATION OF A SEMICONDUCTOR DIE WITH ATTACHED HEAT SINK, the specification of which (check one):

D was filed on as \	United States application serial no	and was amended on		
D was filed onas !	PCT international application no.	and was amended under PCT Article 19 on	·	
I hereby state that I have reviewed referred to above.	and understand the contents of the above-id	entified specification, including the claims, as amer	nded by any ar	mendmen
Laska and adopt the duty to displace	to the U.S. Patent and Trademark Office all	information known to me to be material to the pat	lantahitim of d	h
	"materiality" is defined in Title 37, Code of		emaning of in	ie sunject
certificate or § 365(a) of any PCT inte attached continuation page and have als	rnational application(s) designating at least of so identified helow and on any attached cont esignating at least one country other than the	19 (a)-(d) or § 365(b) of any foreign application(s) one country other than the United States of Americal invision page any foreign application for patent or a United States of America having a filing date before.	a listed below inventor's cer	and on as
Prior foreign/PCT application(s):		•		
	. •		Priority C	laimed
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	· (dny/month/year filed)	Yes	No
(application serial no.)	(filing date)	(status - pending, patented or	ahandoned)	
(application serial no.)	(filing date)	(status - pending, patented or	abandoned)	
I hereby claim the benefit under Title	35, United States Code, § 119(e) of any U	nited States provisional application(s) listed below:		
(provisional application no.)	(filing date)			
(provisional application no.)	(filing date)			
(provisional application no.)	(filing date)			
I hereby appoint the following Regist onnected therewith:	tered Practitioners to prosecute this applicati	ion and to transact all business in the Patent and Tr	rademark Offic	e
David V. Trask, Reg. No. 22,012 Laurence B. Bond, Reg. No. 30,549 Allen C. Turner, Reg. No. 33,041 Robert G. Winkle, Reg. No. 37,474 Michael L. Lynch, Reg. No. 30,871	William S. Britt, Reg. No. 20,969 Joseph A. Walkowski, Reg. No. 28,7 Kent S. Burningham, Reg. No. 30,45 Patrick McBride, Reg. No. 39,295 Lia M. Pappas, Reg. No. 34,095			
ddress all correspondence to:	James R. Duzan, telephone no. (801) 532- TRASK, BRITT & ROSSA P.O. BOX 2550 Salt Lake City, Utah 84110	1922.		
rue; and further that these statements we	ere made with the knowledge that willful fal	nd that all statements made on information and hel se statements and the like so made are punishable l ful false statements may jeopardize the validity of t	by fine or impr	risonmen

Full name of sole inventor: Richard W. Wensel Inventor's signature Date

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